

# DATA SHEET

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**74F64**

4-2-3-2-input AND-OR-invert gate

Product specification

1996 Mar 14

IC15 Data Handbook

# 4-2-3-2-input AND-OR-invert gate

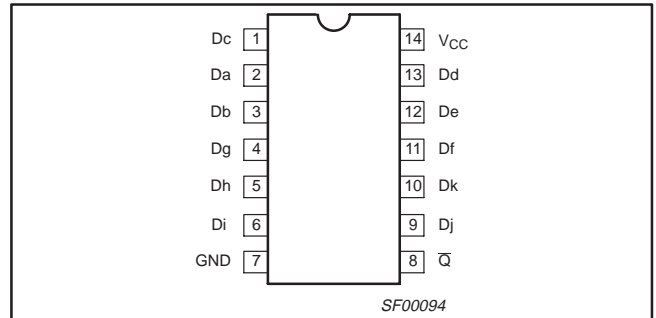
# 74F64

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F64	4.0ns	2.5mA

### ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$ , $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$	PKG. DWG. #
14-pin plastic DIP	N74F64N	SOT27-1
14-pin plastic SO	N74F64D	SOT108-1

### PIN CONFIGURATION

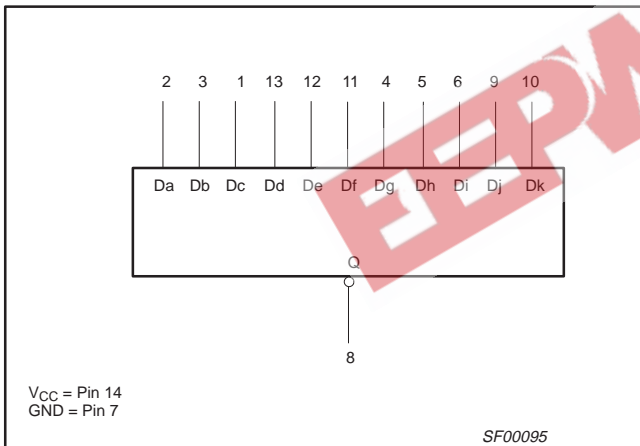


### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

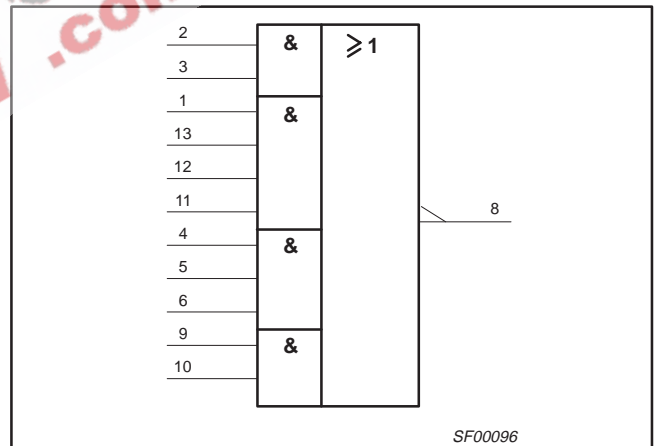
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dn	Data inputs	1.0/1.0	20 $\mu$ A/0.6mA
$\bar{Q}$	Data output	50/33	1.0mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20 $\mu$ A in the High state and 0.6mA in the Low state.

### LOGIC SYMBOL



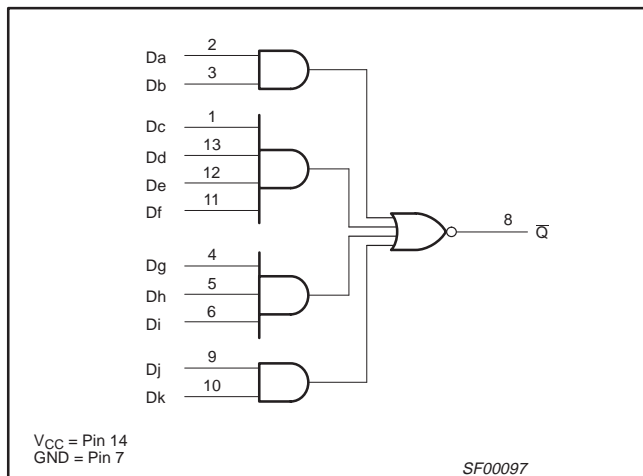
### IEC/IEEE SYMBOL



## 4-2-3-2-input AND-OR-invert gate

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## LOGIC DIAGRAM



## FUNCTION TABLE

INPUTS											OUTPUT
Da	Db	Dc	Dd	De	Df	Dg	Dh	Di	Dj	Dk	$\bar{Q}$
H	H	X	X	X	X	X	X	X	X	X	L
X	X	H	H	H	H	X	X	X	X	X	L
X	X	X	X	X	X	H	H	H	X	X	L
X	X	X	X	X	X	X	X	X	H	H	L
All other combinations											H

## NOTES:

1. H = High voltage level
2. L = Low voltage level
3. X = Don't care

## ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device.  
Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

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## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5.0	5.5	V
$V_{IH}$	High-level input voltage	2.0			V
$V_{IL}$	Low-level input voltage			0.8	V
$I_{IK}$	Input clamp current			-18	mA
$I_{OH}$	High-level output current			-1	mA
$I_{OL}$	Low-level output current			20	mA
$T_{amb}$	Operating free-air temperature range	0		+70	°C

## DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1</sup>	LIMITS			UNIT	
			MIN	TYP <sup>2</sup>	MAX		
$V_{OH}$	High-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}$	$\pm 10\%V_{CC}$	2.5		V	
		$V_{IH} = \text{MIN}, I_{OH} = \text{MAX}$	$\pm 5\%V_{CC}$	2.7	3.4	V	
$V_{OL}$	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}$	$\pm 10\%V_{CC}$		0.30	0.50	V
		$V_{IH} = \text{MIN}, I_{OL} = \text{MAX}$	$\pm 5\%V_{CC}$		0.30	0.50	V
$V_{IK}$	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = I_{IK}$			-0.73	-1.2	V
$I_I$	Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7.0\text{V}$				100	$\mu\text{A}$
$I_{IH}$	High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7\text{V}$				20	$\mu\text{A}$
$I_{IL}$	Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.5\text{V}$				-0.6	mA
$I_{OS}$	Short-circuit output current <sup>3</sup>	$V_{CC} = \text{MAX}$		-60		-150	mA
$I_{CC}$	Supply current (total)	$V_{CC} = \text{MAX}$	$V_{IN} = \text{GND}$		1.9	2.8	mA
			$V_{IN} = 4.5\text{V}$		3.1	4.7	mA

## NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at  $V_{CC} = 5\text{V}$ ,  $T_{amb} = 25^\circ\text{C}$ .
- Not more than one output should be shorted at a time. For testing  $I_{OS}$ , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

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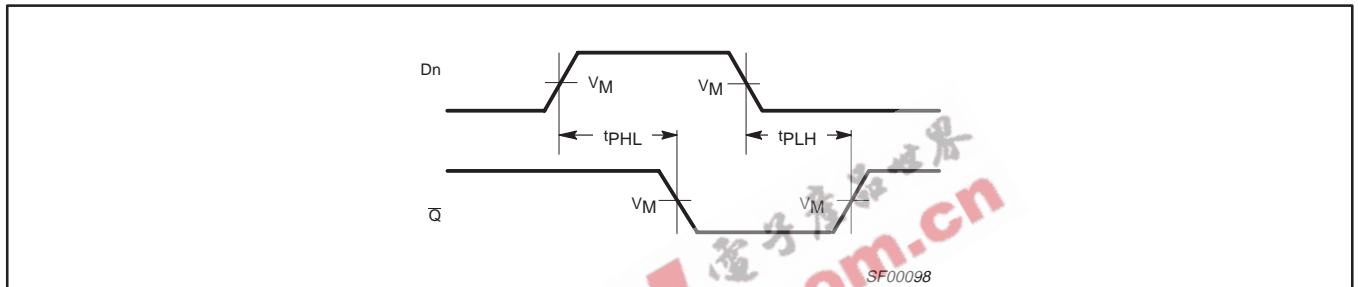
74F64

## AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			V <sub>CC</sub> = +5.0V ± 10% T <sub>amb</sub> = 0°C to +70°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay D <sub>n</sub> to Q̄	Waveform 1	2.5 2.0	4.6 3.2	6.0 4.5	2.5 2.0	7.0 5.5	ns

## AC WAVEFORMS

For all waveforms, V<sub>M</sub> = 1.5V.



Waveform 1. Propagation Delay for Inverting Outputs

## TEST CIRCUIT AND WAVEFORM

**Test Circuit for Totem-Pole Outputs**

**Input Pulse Definition**

**DEFINITIONS:**  
 R<sub>L</sub> = Load resistor; see AC ELECTRICAL CHARACTERISTICS for value.  
 C<sub>L</sub> = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.  
 R<sub>T</sub> = Termination resistance should be equal to Z<sub>OUT</sub> of pulse generators.

family	INPUT PULSE REQUIREMENTS					
	amplitude	V <sub>M</sub>	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

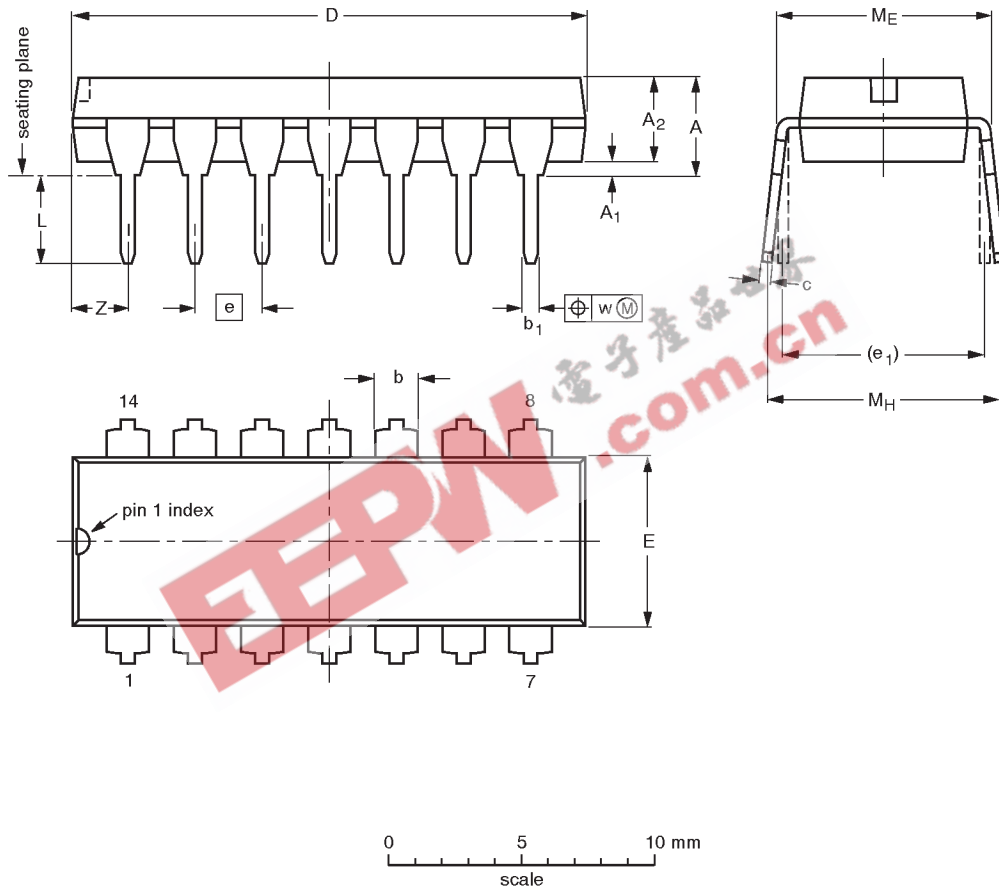
SF00006

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

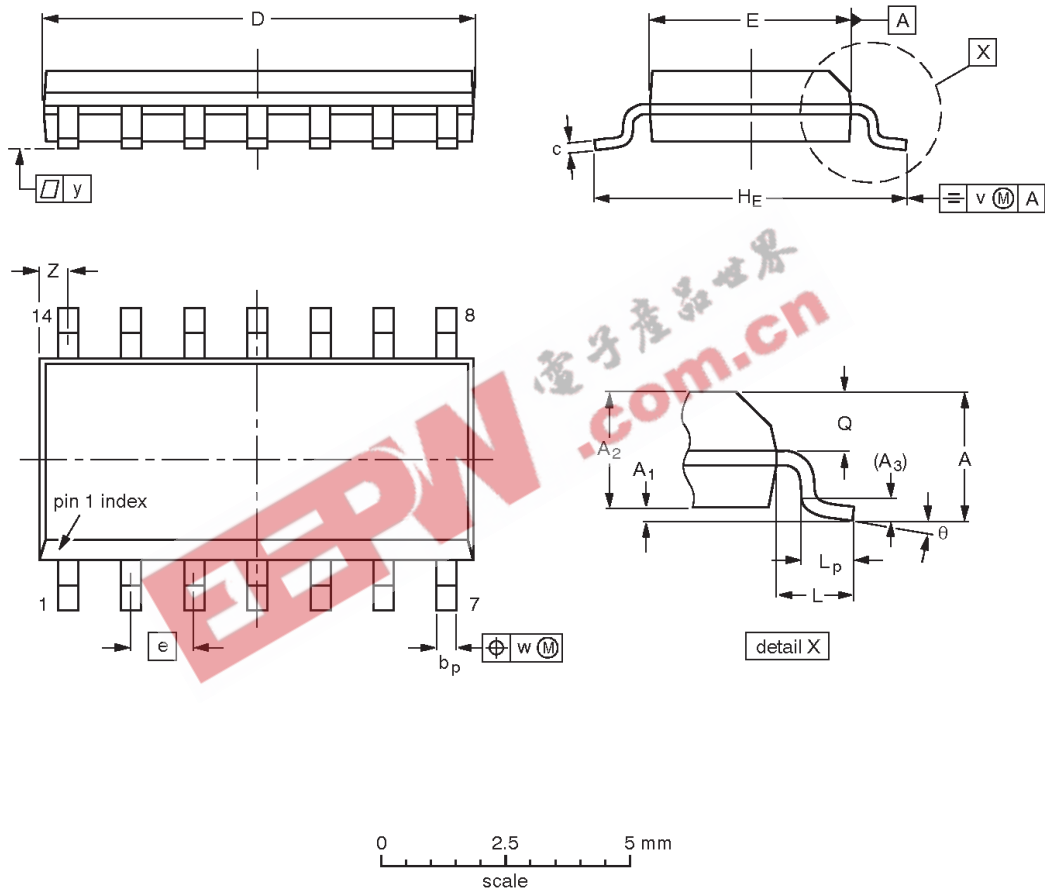
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				95-01-20 97-05-22

## 4-2-3-2-input AND-OR-invert gate

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## DEFINITIONS

Data Sheet Identification	Product Status	Definition
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